



Diamond wheel for back-side-grinding of silicon wafer

Welcome to buy Diamond wheel for back-side-grinding of silicon wafer from us. Every request from customers is being replied within 24 hours.

Wholesale Diamond wheel for back-side-grinding of silicon wafer Factory

Our organization promises all customers with the first-class products and solutions and the most satisfying post-sale service. We warmly welcome our regular and new clients to join us for Popular Design for China Back-Side Diamond Rotating Grinding Wheel for Silicon Wafer, Warmly welcome to cooperate and create with us! we're going to continue to provide merchandise with high-quality and competitive rate. Popular Design for China Silicon Wafer, Rotating Grinding Wheel, It using the world's leading system for reliable operation, a low failure rate, it suitable for Argentina customers choice. Our company is situated within the national civilized cities, the traffic is very convenient, unique geographical and economic conditions. We pursue a people-oriented, meticulous manufacturing, brainstorm, build brilliant" business philosophy. Strict quality management, perfect service, reasonable price in Argentina is our stand on the premise of competition. If necessary, welcome to contact us by our website or phone consultation, we will be happy to serve you.



Wafer thinning wheels are mainly used for thinning and fine grinding of semiconductor wafers. The silicon wafer thinning grinding wheels produced by our company can replace imported products and are used stably on grinding machines in Japan, Germany, the United States, South Korea and domestically produced grinding wheels with superior grinding performance and high cost performance.

Application object: discrete device, integrated circuit substrate silicon wafer and original silicon wafer

processing

Workpiece material: semiconductor materials such as monocrystalline silicon

Processing procedures: back thinning processing, rough grinding processing of front grinding and fine grinding processing

Sanding Diamond Grinding Wheels Our company supplies grinding wheels of various common specifications and shapes, which can be processed according to customer requirements, and customers of other specifications can also process with drawings.

Thinning grinding wheels Silicon wafer thinning grinding wheels are mainly used for thinning and fine grinding of semiconductor wafers. The silicon wafer thinning grinding wheel produced by us can replace imported products and is used stably on grinding machines in Japan, Germany, the United States, South Korea and domestically produced grinding wheels. The grinding wheel has superior grinding performance and high cost performance. Processing objects: discrete devices, integrated circuit substrate silicon wafers and original silicon wafers, etc. Workpiece materials: semiconductor materials such as monocrystalline silicon

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